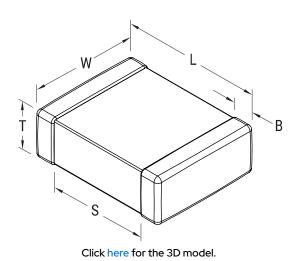




SMD Comm X8G HT150C, Ceramic, 24 pF, 2%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.5 mm



General Information		
Series	SMD Comm X8G HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	3.7 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions		
Chip Size	0603	
L	1.6mm +/-0.15mm	
W	0.8mm +/-0.15mm	
Т	0.8mm +/-0.07mm	
S	0.5mm MIN	
В	0.35mm +/-0.15mm	

Packaging Specifications	
В	0.35mm +/-0.15mm
S	0.5mm MIN
Т	0.8mm +/-0.07mm
VV	0.011111 1/ -0.1311111

Specifications	
Capacitance	24 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	2%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Packaging	T&R, 330mm, Paper Tape	Reference to +25°C and 0 VDC Applied (TCC)
Packaging Quantity	15000	Dissipation Factor (
		Aging Rate

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